



Material Content Data Sheet



Sales Product Name		1EDN7511B		Issued		4. July 2019		
MA#		MA005348198						
Package		PG-SOT23-6-2		Weight*		18.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.383	7.43	7.43	74346	74346
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		117	
	non noble metal	zinc	7440-66-6	0.009	0.05		470	
	non noble metal	iron	7439-89-6	0.175	0.94		9398	
wire	non noble metal	copper	7440-50-8	7.097	38.16	39.16	381598	391583
	noble metal	gold	7440-57-5	0.082	0.44	0.44	4416	4416
	encapsulation	organic material	carbon black	1333-86-4	0.018	0.10		991
encapsulation	plastics	epoxy resin	-	1.409	7.58		75789	
	inorganic material	silicondioxide	60676-86-0	7.784	41.85	49.53	418569	495349
leadfinish	non noble metal	tin	7440-31-5	0.465	2.50	2.50	24993	24993
plating	noble metal	silver	7440-22-4	0.167	0.90	0.90	8983	8983
tape	plastics	epoxy resin	-	0.003	0.02		165	
	inorganic material	silicondioxide	60676-86-0	0.003	0.02	0.04	165	330
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com